Advance Information N-Channel SUPERFET[®] III Easy-Drive MOSFET

650 V, 7 A, 500 m Ω

Description

SuperFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SuperFET III MOSFET Easy-drive series helps manage EMI issues and allows for easier design implementation.

Features

- 700 V @ $T_J = 150^{\circ}C$
- Typ. $R_{DS(on)} = TBD m\Omega$
- Ultra Low Gate Charge (Typ. Q_g = TBD nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = TBD pF)
- 100% Avalanche Tested
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies

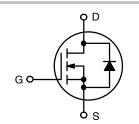
This document contains information on a new product. Specifications and information herein are subject to change without notice.



ON Semiconductor®

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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	500 mΩ	TBD A

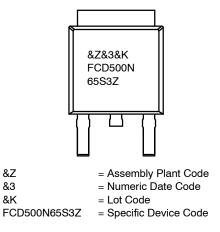


N-Channel MOSFET



D-PAK (DPAK3 (TO-252 3LD)) CASE 369AS

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter Drain-to-Source Voltage		Value	Unit	
V _{DSS}			650	V	
V _{GS}	Gate-to-Source Voltage	DC	±30	V	
		AC (f > 1 Hz)	±30	V	
ID	Drain Current	Continuous (T _C = 25°C)	7	А	
		Continuous (T _C = 100°C)	4.6	1	
I _{DM}	Drain Current	Pulsed (Note 1)	17.5	А	
E _{AS}	Single Pulsed Avalanche Energy (Not	TBD	mJ		
I _{AS}	Avalanche Current (Note 2)	TBD	А		
E _{AR}	Repetitive Avalanche Energy (Note 1)	TBD	mJ		
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)		20	1	
PD	Power Dissipation	(T _C = 25°C)	TBD	W/°C	
		Derate Above 25°C	TBD		
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
ΤL	Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from case for 10 s)		300	°C	

ABSOLUTE MAXIMUM RATINGS (T_J = 25°C, unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. I_{AS} = 1.6 A, R_G = 25 Ω , starting T_J = 25°C.

3. $I_{SD} \leq$ 3 A, di/dt \leq 200 A/µs, V_{DD} \leq 400 V, starting T_J = 25°C.

THERMAL RESISTANCE RATINGS

Symbol	Symbol Parameter		Unit
$R_{ ext{ heta}JC}$	R _{θJC} Junction-to-Case, Steady State		°C/W
$R_{\theta JA}$	Junction-to-Ambient, Steady State (Note 4)	43	

4. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θJA} is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2 oz copper.

PACKAGE MARKING AND ORDERING INFORMATION

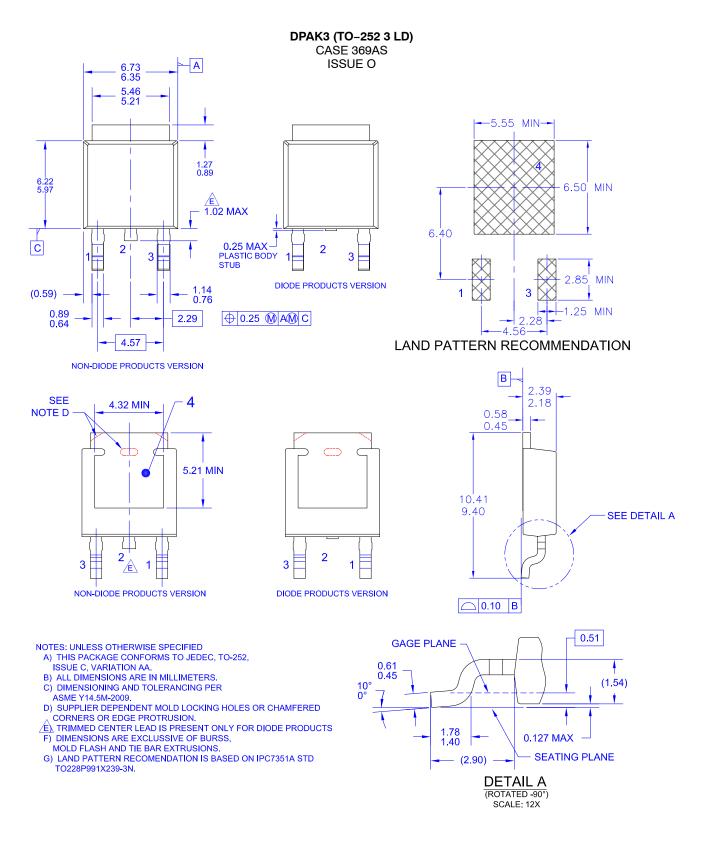
Part Number	Top Marking	Package	Reel Size	Tape Width	Shipping (Qty / Packing)
FCD500N65S3Z	FCD500N65S3Z	D-PAK (DPAK3 (TO-252 3LD)) (Pb-Free / Halogen Free)	330 mm	16 mm	2500 / Tape & Reel

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS					
BV _{DSS}	Drain to Source Breakdown Voltage	V_{GS} = 0 V, I_D = 1 mA, T_J = 25°C	650	-	-	V
		V_{GS} = 0 V, I_{D} = 1 mA, T_{J} = 150°C	700	-	_	V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D = 1$ mA, Referenced to $25^{\circ}C$	-	TBD	-	V/°C
I _{DSS}	SS Zero Gate Voltage Drain Current	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μA
		$V_{DS} = 520 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	TBD	-	
I _{GSS}	Gate to Body Leakage Current	V_{GS} = ±30 V, V_{DS} = 0 V	-	-	±100	nA
ON CHARACTE	RISTICS	-				
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 0.7 \text{ mA}$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V_{GS} = 10 V, I _D = 3.5 A	-	TBD	500	mΩ
9 _{FS}	Forward Transconductance	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 3.5 \text{ A}$	-	TBD	-	S
YNAMIC CHA	RACTERISTICS	-				
C _{iss}	Input Capacitance	V_{DS} = 400 V, V_{GS} = 0 V, f = 1 MHz	-	TBD	-	pF
Coss	Output Capacitance		-	TBD	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	TBD	-	pF
C _{oss(er.)}	Energy Related Output Capacitance	V_{DS} = 0 V to 400 V, V_{GS} = 0 V	-	TBD	-	pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 400 V, I _D = 3.5 A, V _{GS} = 10 V (Note 5)	-	TBD	-	nC
Q _{gs}	Gate to Source Gate Charge		-	TBD	_	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	TBD	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	TBD	-	Ω
WITCHING CH	IARACTERISTICS	-				
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 3.5 \text{ A},$	-	TBD	-	ns
t _r	Turn-On Rise Time	V _{GS} = 10 V, R _g = 4.7 Ω (Note 5)	-	TBD	-	ns
t _{d(off)}	Turn-Off Delay Time		-	TBD	_	ns
t _f	Turn-Off Fall Time		-	TBD	_	ns
SOURCE-DRAI	N DIODE CHARACTERISTICS	•				
۱ _S	Maximum Continuous Source to Drain Diode Forward Current		-	-	7	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		-	-	17.5	А
V _{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I _{SD} = 3.5 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 3.5 A,	-	TBD	-	Ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/µs	-	TBD	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 5. Essentially independent of operating temperature typical characteristics.

PACKAGE DIMENSIONS



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